



P-Channel 20 V (D-S) MOSFET

MOSFET PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a Q _g (Typ		
- 20	$0.112 \text{ at V}_{GS} = -4.5 \text{ V}$	- 3.1	3.3 nC	
- 20	0.142 at $V_{GS} = -2.5 \text{ V}$	- 2.7	3.3 IIC	

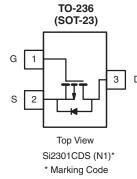
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

· Load Switch



Ordering Information: Si2301CDS-T1-E3 (Lead (Pb)-free)

Si2301CDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 20	V	
Gate-Source Voltage		V _{GS}	± 8		
	T _C = 25 °C		- 3.1		
Continuous Drain Current (T _{.J} = 150 °C)	T _C = 70 °C		- 2.5		
Continuous Diain Current (1) = 130 C)	T _A = 25 °C	I _D	- 2.3 ^{b, c}		
	T _A = 70 °C		- 1.8 ^{b, c}	А	
Pulsed Drain Current		I _{DM} - 10	- 10		
Continuous Source-Drain Diode Current	T _C = 25 °C	I-	- 1.3		
Continuous Source-Diam Diode Current	T _A = 25 °C	I _S	- 0.72 ^{b, c}		
	T _C = 25 °C		1.6		
Maximum Davier Dissination	T _C = 70 °C	ь Г	1.0	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	0.86 ^{b, c}	VV	
	T _A = 70 °C		0.55 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R _{thJA}	120	145	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	62	78	- C/VV	

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 175 $^{\circ}\text{C/W}.$

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	ce Breakdown Voltage V_{DS} $V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		- 20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A		- 18		\//06
$\Delta V_{GS(th)}$ Temperature Coefficient $\Delta V_{GS(th)}/T_J$		I _D = - 250 μA		2.2		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	- 0.4		- 1	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
Zana Oata Wallana Busin Oamant		V _{DS} = - 20 V, V _{GS} = 0 V			- 1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			- 10	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 6			Α
Durin Course On Olate Desisters of		$V_{GS} = -4.5 \text{ V}, I_D = -2.8 \text{ A}$		0.090	0.112	Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -2.5 \text{ V}, I_D = -2.0 \text{ A}$		0.110	0.142	
Forward Transconductance ^a g _{fs}		V _{DS} = - 5 V, I _D = - 2.8 A		9.5		S
Dynamic ^b				1		
Input Capacitance	C _{iss}			405		
Output Capacitance	C _{oss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		75		pF
Reverse Transfer Capacitance	C _{rss}			55		
Total Octo Observe		$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -3 \text{ A}$		5.5	10	
Total Gate Charge	Qg			3.3	6	
Gate-Source Charge	Q _{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -2.5 \text{ V}, I_{D} = -3 \text{ A}$		0.7		nC
Gate-Drain Charge	Q _{gd}			1.3		1
Gate Resistance	R_{g}	f = 1 MHz		6.0		Ω
Turn-On Delay Time	t _{d(on)}			11	20	
Rise Time	t _r	V_{DD} = - 10 V, R_L = 10 Ω		35	60	ns
Turn-Off Delay Time	t _{d(off)}	$I_D = -1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		30	50	
Fall Time	t _f			10	20	
Drain-Source Body Diode Characteristi	cs			1		
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 1.3	
Pulse Diode Forward Current ^a	I _{SM}				- 10	_ A
Body Diode Voltage	oltage V _{SD} I _S = - 0.7 A			- 0.8	- 1.2	٧
Body Diode Reverse Recovery Time	t _{rr}			30	50	ns
Body Diode Reverse Recovery Charge	ecovery Charge Q _{rr}			25	50	nC
Reverse Recovery Fall Time	t _a	$I_F = -3.0 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		15		
Reverse Recovery Rise Time	-			15		ns

Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

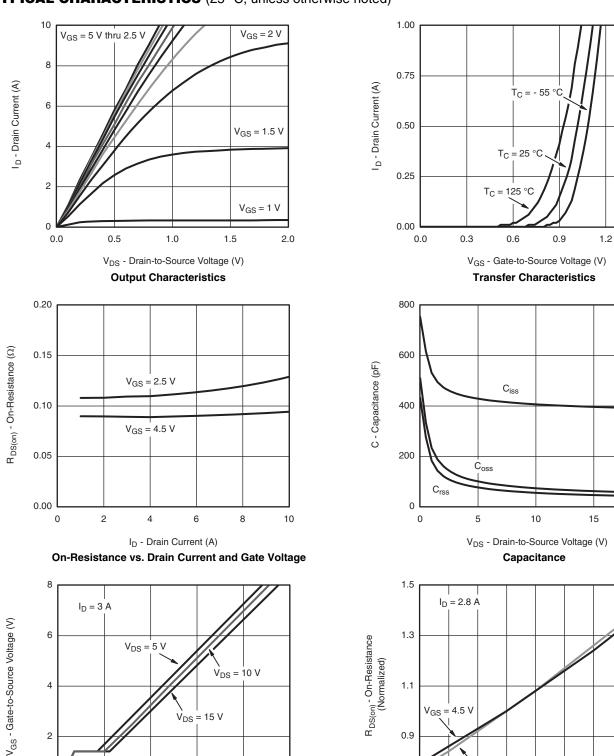
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

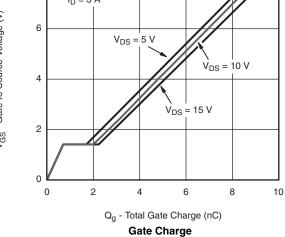
1.5

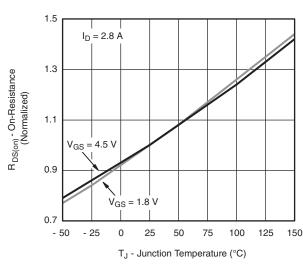
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





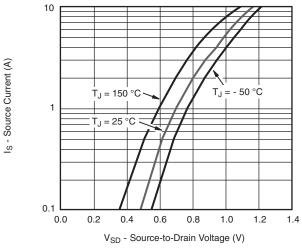


On-Resistance vs. Junction Temperature

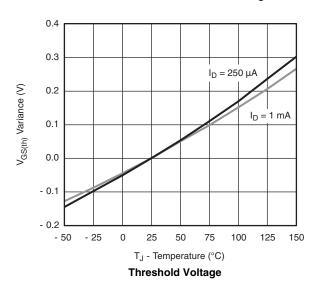
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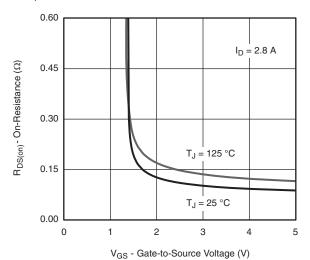
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

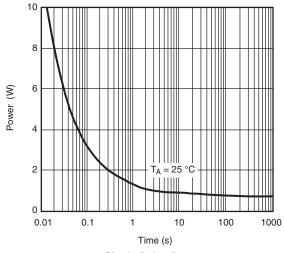


Source-Drain Diode Forward Voltage

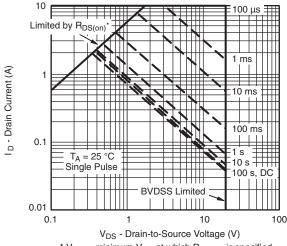




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power

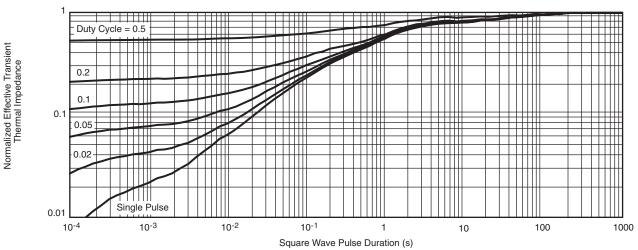


 * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

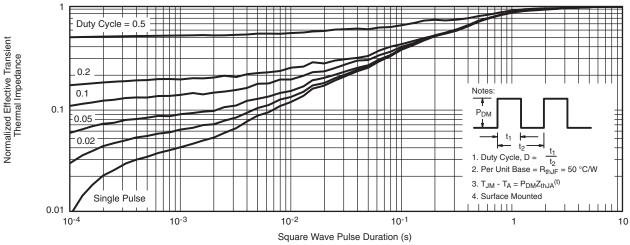
Safe Operating Area



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOT-23 (TO-236): 3-LEAD







Dim	MILLIMETERS		INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	

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RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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